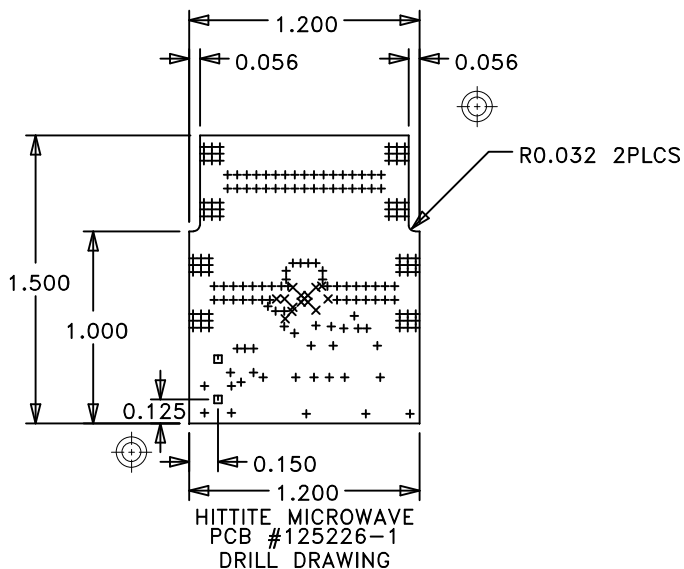
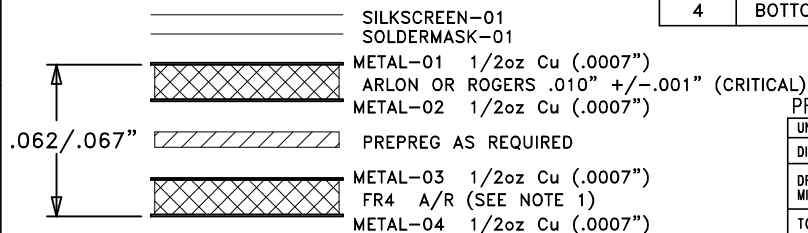


DO NOT SCALE PRINT



SIZE	QTY	SYM	PLATED	TOL
10	15	✕	YES	+/-3
14	178	+	YES	+/-3
43	2	□	YES	+/-3

LAYER	DESCRIPTION
1	RF/GND PLANE
2	GND PLANE
3	POWER/GND PLANE
4	BOTTOM GND PLANE



LAYER STACKUP

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:	
DIMENSIONS ARE IN INCHES (MM)	
DRAWING PRACTICES PER MIL-STD-100	
TOLERANCES:	
.XX	+/- 0.010
.XXX	+/- 0.005
.XXXX	+/- 0.002
ANGLES	+/- .5 DEG

DWN BY:
MARTIN LYONS
ENGINEER:
FATIH KOCER



HITTITE MICROWAVE CORPORATION
20 Alpha Road Chelmsford, MA 01824

TITLE
PCB, EVAL,
HMC5119LP3E, HMC5120LP3E

SIZE	CODE ID NO.	DRAWING NO.	REV
A	1CN88	125226	1

SCALE: WT SHEET 1 of 1

REVISION				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	03/06/09	M.LYONS

NOTES:

UNLESS OTHERWISE SPECIFIED

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES, TOPSIDE ONLY. FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ±.003" OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ±.003" MAX.
7. BOARD WARPAGE: <.010" PER LINEAR INCH.
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK.
9. TOLERANCE ON PCB ROUTE IS ±.005".
10. PLATING THICKNESS .002"±.0005 FOR METAL-01 AND METAL-04.
11. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ±.004 MAX.
12. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPERATION.
13. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
14. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
15. MANUFACTURE PER IPC-600 CLASS 2.
16. CRITICAL LINE WIDTH = .016" +/--.001" ADJUST PROCESS TO ACHIEVE WIDTH.